

BEST AVAILABLE COPY

Jun 22 2006 5:20PM

POSZ LAW GROUP

7037079112

p. 4

Serial No. 10/701,441

Attorney Docket No. 01-304-DIV

AMENDMENTS TO THE SPECIFICATION

Please amend the paragraph beginning at page 1, line 5, as follows:

This application is a divisional application of U.S. Patent Application Serial No. 10/166,731, which was filed on June 12, 2002, now US patent 6,680,441 which is based on and incorporates herein by reference Japanese Patent Applications No. 2001-179118 filed on Jun. 13, 2001, No. 2001-199392 filed on Jun. 29, 2001, No. 2001-204023 filed on Jul. 4, 2001, and No. 2002-62394 filed on Mar. 7, 2002.

Please amend the paragraph that begins on page 35, line 2 (the abstract) as follows:

A manufacturing method of a printed wiring board having an embedded electric device is manufactured as follows. A first resin film having an opening or a sheet member having a recess is piled with a plurality of second resin films, on which a plurality of conductive layers are formed. The first and second resin films and the sheet member include thermoplastic resin. An electric device is inserted in the opening or the recess. Then, the piled body including the electric device is pressed and heated to integrate the piled body. When the piled body is pressed and heated, a plurality of electrodes of the electric device are electrically connected to the conductive layers while the first and second resin films and the sheet member plastically deformed to seal the electric device.